

Amendment Under 37 C.F.R. §1.111  
Serial No. 10/664,930  
Attorney Docket No. 021385B

**AMENDMENTS TO THE CLAIMS:**

**Listing of claims:**

This listing of claims replaces all prior versions and listings of claims in the application.

Claim 1 (Currently Amended): A test apparatus used for ~~evaluating~~ testing a multilayer wiring board ~~formed by successively being fabricated by~~ stacking wiring layers successively, said test apparatus comprising:

~~a probe part configured to be connected to an incomplete~~ probe that detects defects in the multilayer wiring board that is in a half finished state before completion under fabrication ; and

~~a supplementary part supplementing an element of an element supplementing unit that mounts additional elements on the multilayer wiring board, said incomplete multilayer wiring board lacking said element~~ under fabrication when no defect is detected by the probe.

Claim 2 (Currently Amended): The test apparatus as claimed in claim 1, wherein the ~~supplementary part includes layer wiring of the multilayer wiring board, said incomplete multilayer wiring board lacking said layer wiring~~ additional elements to be mounted are included in the element supplementing unit.

Claim 3 (New): The test apparatus as claimed in claim 1, wherein the element supplementing unit includes

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a first section arranged to face a first side of the multilayer wiring board under fabrication to mount the additional elements on the first side; and

a second section arranged to face a second side of the multilayer wiring board under fabrication to mount the additional elements on the second side.

Claim 4 (New): A method of fabricating a multilayer wiring board, comprising:

a first step of testing the multilayer wiring board under fabrication to detect whether defects exist;

a second step of mounting additional elements on the multilayer wiring board under fabrication when no defect is detected;

a third step of testing the multilayer wiring board including the additionally mounted elements; and

a fourth step of continuing or stopping mounting of further additional elements according to testing results of the third step.

Claim 5 (New): The method as claimed in claim 4, wherein a test apparatus is provided to test the multilayer wiring board under fabrication and to mount the additional elements, said test apparatus comprising a probe for testing and an element supplementing unit for mounting the additional elements.

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Claim 6 (New): The method as claimed in claim 5, wherein the additional elements to be mounted are carried by the element supplementing unit.

Claim 7 (New): The method as claimed in claim 4, wherein testing and mounting of the additional elements are performed on opposite two sides of the multilayer wiring board under fabrication.